

*Amendments to the Claims*

The listing of claims will replace all prior versions, and listings of claims in the application.

1-11. *(cancelled)*

12. *(currently amended)* A lithography system configured to reduce wafer slipping, comprising:

(a) a wafer chuck configured to receive a wafer; and

(b) an expander comprising an expandable annular tube coupled to the wafer chuck and configured to expand the wafer chuck without substantially expanding the wafer, such that an initial stress at an interface between the wafer and the wafer chuck is created.

13. *(canceled)*

14. *(currently amended)* The system of claim ~~[[13]]~~ 12, wherein said annular tube is coupled to an outer edge of said wafer chuck.

15. *(withdrawn)* The system of claim 13, wherein said annular ring fits within a cavity in said wafer chuck.

16. - 22. *(cancelled)*

23.     *(original)* The system of claim 12, wherein said expander is configured to expand said wafer chuck in a uniform manner.